

Thermal Compression Bonding Equipment

HTB-MS/MM

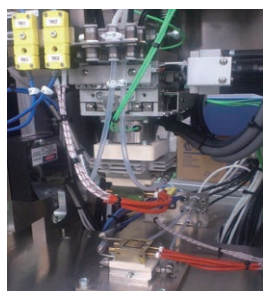


Simple pressurizing heating bonding equipment
suitable for the development of semiconductor,
power device and film material at research
institutes, universities, etc.

Single Head Thermal Compression Bonder : HTB-MS/MM

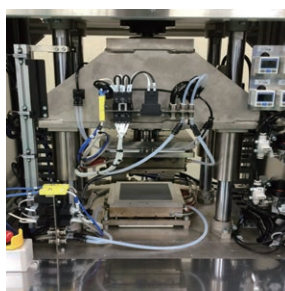
HTB-MS

Stage Size □30mm
MAX1000N



HTB-MM

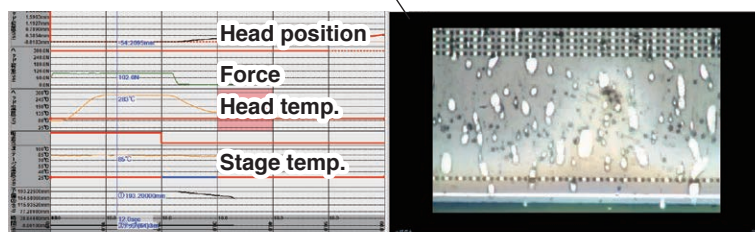
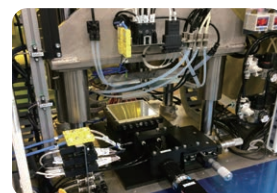
Stage Size □100mm
MAX5000N



Observation Unit (option)

*Visualize the behavior
during bonding!*

Videos synced with profile



Standard specifications

Machine name		Thermal Compression Bonder	
Type		HTB-MS	HTB-MM
Stage size		□30*30 mm	□100*100mm(Constant Heater)
Heating range(Head)		Constant heater : RT~300°C±15°C Pulse heater (option)	Constant heater : RT~300°C±15°C Pulse heater (option*1)
Heating range(Stage)		Constant heater : RT~300°C±15°C Pulse heater (option)	Constant heater : RT~300°C±15°C Pulse heater (option*2)
Head Force		10N~1000N ±5%	100N~5000N ±5%(~500N)±15%(501~5000N)
Parallelism degree between head and stage		±3μm	±3μm/□20mm, ±20μm/□100mm
Outer dimensions		Width:600mm*Depth:600mm* Height :1550mm (excl. signal tower and operation part)	Width:600mm*Depth:600mm* Height:1550mm (excl. signal tower and operation part)
Weight		Approx.200Kg	Approx.280Kg
Power	Power	3-phase AC200V(50/60Hz) Two power lines (30A and 15A) required	3-phase AC200V(50/60Hz) Two power lines (30A and 15A) required
	Dry air	0.5MPa	0.5MPa, 245L/min
Options		Pulse heater(head・stage) Max.450°C Bonding observation unit	Pulse heater(head*1, stage*2) MAX450°C N2 purge chamber Bonding observation unit

Contact us

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DESIGN

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●Specifications and appearance contained herein are subject to change without prior notice.

●The contents of this catalog are as of April 2023